12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20131220003
Conversion to Cu bond wire
Change Notification / Sample Request

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The changes discussed within this PCN will not take effect any earlier than **90** days from the date of this notification, unless customer agreement has been reached on an earlier implementation of the change. This notification period is per TI's standard process.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services
Phone: +1(214) 480-6037
Fax: +1(214) 480-6659

PCN# 20131220003
Attachment: 1

Products Affected:

According to our records, there are the affected device(s) that you have purchased within the past twenty-four (24) months. Technical details of this Product Change follow on the next page(s).

PCN Number:	20131220003	**PCN Date:**	12/27/2013
Title:	Conversion to Cu bond wire		
Customer Contact:	PCN Manager	**Phone:** +1(214)480-6037	**Dept:** Quality Services
Proposed 1st Ship Date:	03/27/2014	**Estimated Sample Availability:**	12/27/2013

Change Type:

☐	Assembly Site	☒	Assembly Process	☒	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☐	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☐	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☐	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of Cu as a bond wire option for the selected devices shown below. All listed devices will remain in current assembly facility and there will be no other BOM changes.

Reason for Change:

Continuity of supply.

1) To align with world technology trends and use wiring with enhanced mechanical and electrical properties
2) Maximize flexibility within our Assembly/Test production sites.
3) Cu is easier to obtain and stock

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

None affecting physical device marking. The 'REV' number on the labels will change for the CC112x/CC1175 and the CC2530FxxCRHA products.

Note that the following register changes will apply to the following products:

CC112x/CC1175:
Register 0x90 PARTVERSION. The new Reset value is 0x23.

CC2530F12CRHA and CC2530F25CRHA:
Register 0x6249 CHVER. The chip revision number will change.

Product Affected:			
CC1120RHBR	CC1125ARHBR	CC1175RHBT	CC1201RHBT
CC1120RHBT	CC1125RHBR	CC1200RHBR	CC2530F12CRHA
CC1121RHBR	CC1125RHBT	CC1200RHBT	CC2530F25CRHA
CC1121RHBT	CC1175RHBR	CC1201RHBR	

Reference Qualification Data

This qualification has been developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle: CC2533F96RHA (MSL 3-260C)

Package Construction Details

Assembly Site:	Clark AT	Mold Compound:	4208625
# Pins-Designator, Family:	40-RHA, VQFN	Mount Compound:	4207123
Lead Finish	NiPdAu	Bond Wire:	0.8mil Cu

Qualification: ☐ **Plan** ☒ **Test Results**

Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
** High Temp Operating Life	125C (168, 500, 1000 Hrs)	39/0	39/0	38/0
High Temp. Storage Bake	150C (168, 300, 600 hrs)	77/0	77/0	77/0
**Biased Temp. Humidity	85C/85%RH (168, 600, 800 Hrs).	26/0	26/0	25/0
**Unbiased HAST	110C/85%RH/17.7 psia (96, 264 hrs)	77/0	77/0	77/0
**T/C -65C/150C	-65C/+150C (500 Cyc)	26/0	26/0	25/0
**T/C -55C/125C	-55C/+125C (200, 700 Cyc)	77/0	77/0	77/0
ESD CDM	+/- 100V, 250V, 500V	3/0	3/0	3/0
ESD HBM	+/- 500V, 1000V	3/0	3/0	3/0
Latch-up	(per JESD78)	6/0	3/0	3/0

Notes **- Preconditioning sequence: Level 3-260C.

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com